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(54) Title: ELECTRICALLY CONDUCTIVE LAMINATE STRUCTURES, ELECTRICAL INTERCONNECTS, AND METHOD OF FORMING ELECTRICAL INTERCONNECTS

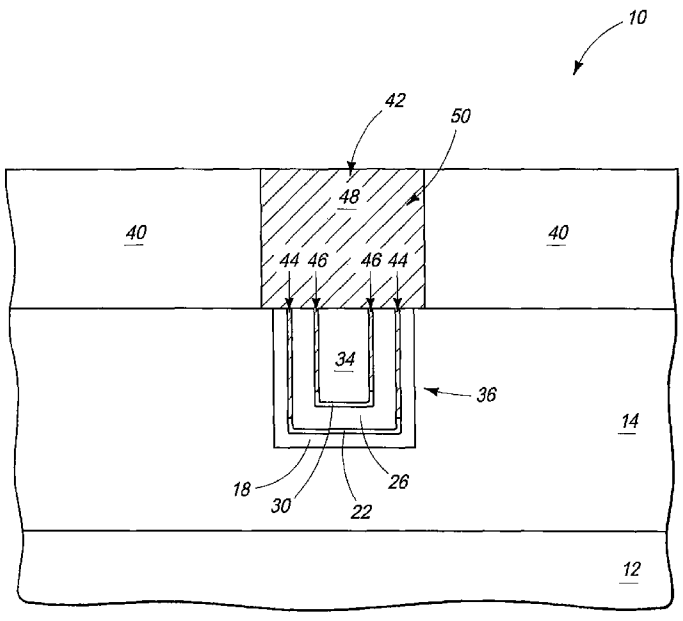


Fig. 1

(57) Abstract: Some embodiments include electrical interconnects. The interconnects may contain laminate structures having a graphene region sandwiched between non-graphene regions. In some embodiments the graphene and non-graphene regions may be nested within one another. In some embodiments an electrically insulative material may be over an upper surface of the laminate structure, and an opening may extend through the insulative material to a portion of the laminate structure. Electrically conductive material may be within the opening and in electrical contact with at least one of the non-graphene regions of the laminate structure. Some embodiments include methods of forming electrical interconnects in which non-graphene material and graphene are alternately formed within a trench to form nested non-graphene and graphene regions.

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